



PK654 (v1.0) May 5, 2014

100% Material Declaration Data Sheet for 7 Series CPG236 Package

Average Weight: 0.2714g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.017861	6.580
	Silicon	7440-21-3	100.00		0.017861	
Silver Epoxy					0.005739	2.110
	Silver	7440-22-4	77.50		0.004448	
	Bismaleimide monomer	Trade Secret	15.00		0.000861	
	Acrylate monomer	Trade Secret	7.50		0.000430	
Copper Wire					0.002744	1.010
	Copper	7440-50-8	98.25		0.002696	
	Palladium	7440-05-3	1.75		0.000048	
Mold Compound					0.120617	44.440
	Epoxy Resin	Trade Secret	7.50		0.009046	
	Phenol Resin A	9003-35-4	3.00		0.003619	
	Phenol Resin B	Trade Secret	3.00		0.003619	
	Silica (Amorphous) A	60676-86-0	67.95		0.081959	
	Silica (Amorphous) B	7631-86-9	15.00		0.018093	
	Metal Hydroxide	Trade Secret	3.00		0.003619	
Carbon Black	1333-86-4	0.55		0.000663		
Solder Ball					0.024684	9.100
	Tin	7440-31-5	98.50		0.024314	
	Silver	7440-22-4	1.00		0.000247	
	Copper	7440-50-8	0.50		0.000123	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					0.099755	36.760
	Gold	7440-57-5	1.82		0.001815	
	Nickel	7440-02-0	11.19		0.011160	
	Copper Foil	7440-50-8	12.25		0.012216	
	Copper Plating	7440-50-8	23.60		0.023542	
	Continuous Filament Fiber Glass	65997-17-3	12.30		0.012270	
	Non Halogen Fire Retardent	Trade Secret	2.37		0.002362	
	BT Core	105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-50-8	33.91		0.033830	
Solder Mask	147-14-8 7727-43-7 7631-86-9 14807-96-6 112-15-2 34590-94-8 103429-90-9 64742-94-5 25551-13-7	2.57		0.002559		

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/05/2014	1.0	Xilinx Initial Release

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